

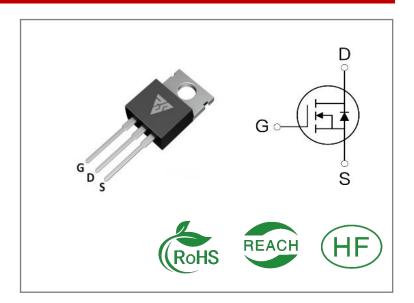
ID	R <sub>DS</sub> (ON)(Typ)	VDSS
105A	9.8mΩ	150V

## **Applications:**

- Load Switch
- PWM Applications
- Power Managment

#### **Features:**

- Fast switching speed
- 100% avalanche tested
- Improved dv/dt capability



**Ordering Information** 

Part Number	Package	Marking	Packing	Qty.
RS150N105T	T0-220	RS150N105T	Tube	50 PCS

## Absolute Maximun Ratings Tc= 25°C unless otherwise specified

Symbol	Parameter	RS150N105T	Units
VDSS	Drain-to-Source Voltage	150	V
ID	Continuous Drain Current TC=25℃	105	
ID	Continuous Drain Current TC=100℃	75	А
IDM	Pulsed Drain Current	420	
PD	Power Dissipation	380	W
VGS	Gate- to- Source Voltage	±20	V
EAS	Single Pulse Avalanche Engergy L = 0.3mH,VDS = 50V, RG = 25 $\Omega$ , Tj = 25 $^{\circ}$ C	1000	mJ
	Maximum Temperature for Soldering		
TL TPKG	Leads at 0.063in(1.6mm)from Case for 10 seconds Package Body for 10 seconds	300 260	$^{\circ}$
TJ and TSTG	Operating Junction and Storage Temperature Range	-55 to 150	

<sup>\*</sup> Drain Current Limited by Maximum Junction Temperature

Caution: Stresses greater than those listed in the "Absolute Maximum Ratings" Table may cause permanent damage to the device.



### **Thermal Resistance**

Symbol	Parameter	RS150N105T	Units	Test Conditions
RθJC	Junction-to-Case	0.36	°C/W	Drain lead soldered to water cooled heatsink, PD adjusted for a peak junction temperature of + 1 5 0 $^{\circ}$ C
RθJA	Junction-to- Ambient	60		1 cubic foot chamber,free air.

# **OFF Characteristics** TJ= 25°C unless otherwise specified

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
BVDSS	Drain- to- source Breakdown Voltage	150			V	VGS=0V,ID=250μ A
IDSS	Drain- to- Source Leakage Current			1	μΑ	VDS=150V,VGS= 0V
IGSS	Gate- to- Source Forward Leakage			100	- A	VGS=20V ,VDS=0 V
1033	Gate- to- Source Reverse Leakage			-100	nA	VGS=-20V ,VDS= 0V

# ON Characteristics TJ=25°C unless otherwise specified

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
RDS(on)	Static Drain- to- Source On- Resistance		9.8	11	mΩ	VGS=10V,ID=60A
VGS(TH	Gate Threshold Voltage	3.6		5.0	V	VGS=VDS,ID=25 0μA

# Resistive Switching Characteristics Essentially independent of operating temperature

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
td(ON)	Turn- on Delay Time		45			\/DC
trise	Rise Time		70			VDS=50V ID=40A
td(OFF)	Turn- OFF Delay Time		110		nS	RG=2.5Ω VGS=10V
tfall	Fall Time		90			VG3-10V



**Dynamic Characteristics** Essentially independent of operating temperature

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
Ciss	Input Capacitance		7000			VGS= 0V
Coss	Output Capacitance		480		pF	VDS=50V
Crss	Reverse Transfer Capacitance		210			f=1MHz
Qg	Total Gate Charge		85			VDS= 100V
Qgs	Gate- to- Source Charge		15		nC	ID=40A
Qgd	Gate-to-Drain(" Miller") Charge		25			VGS=10V

### **Source-Drain Diode Characteristics**

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
IS	Continuous Source Current			105	Α	Integral pn- diode
ISM	Maximum Pulsed Current			420	Α	in MOSFET
VSD	Diode Forward Voltage			1.2	V	IS=60A,VGS=0V
trr	Reverse Recovery Time		110		nS	VGS=0V
Qrr	Reverse Recovery Charge		0.55		μC	IS=30A di/dt=100A/μs

#### Notes:

<sup>\* 1.</sup> Repetitive rating, pulse width limited by maximum junction temperature.

<sup>\* 2.</sup> Pulse Test: Pulse width ≤ 300μs, Duty Cycle ≤ 1.5%



## **Typical Feature Curve**

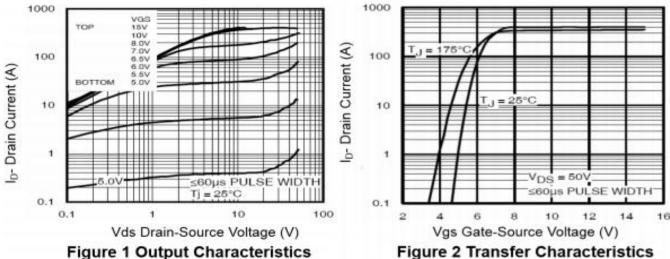
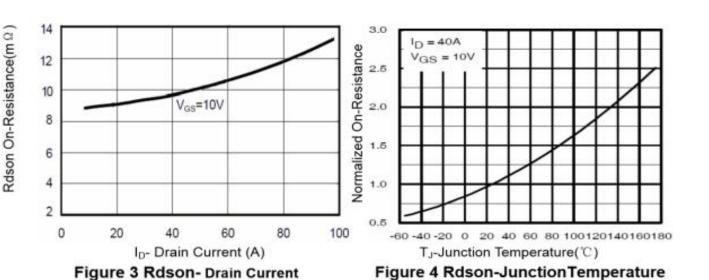


Figure 1 Output Characteristics



ID=40A Vgs Gate-Source Voltage (V) 16 12 0 40 80 120 160 200 Qg Gate Charge (nC) Figure 5 Gate Charge

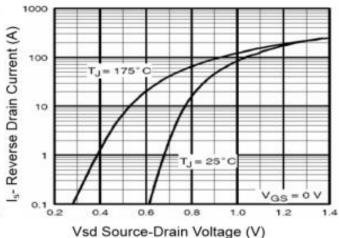


Figure 6 Source- Drain Diode Forward

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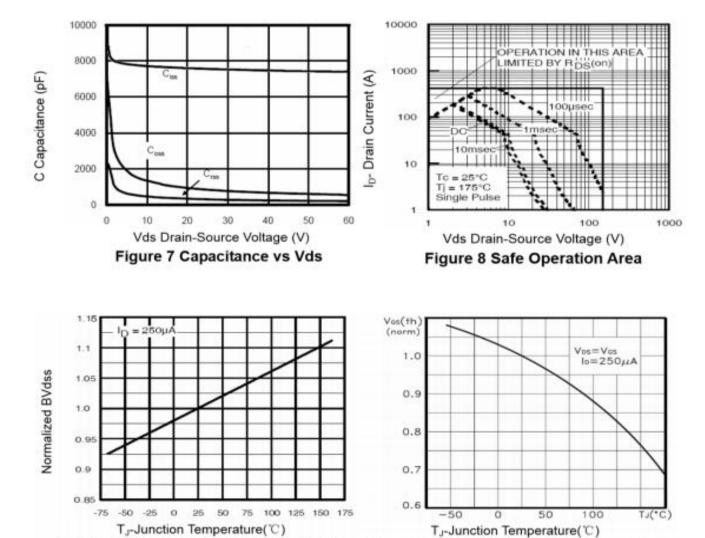


Figure 9 BV<sub>DSS</sub> vs Junction Temperature Figure 10 V<sub>GS(th)</sub> vs Junction Temperature

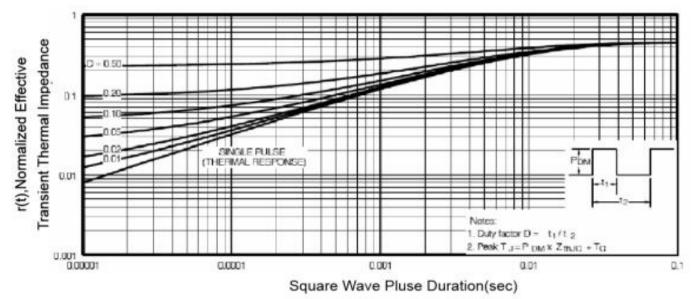


Figure 11 Normalized Maximum Transient Thermal Impedance



### **Test ircuits and Waveforms**

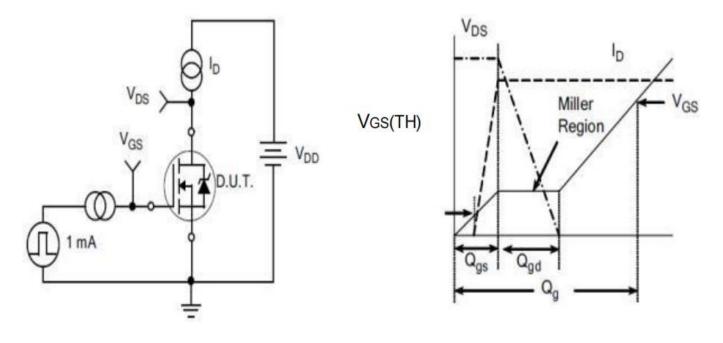


Figure A.
Gate Charge Test Circuit

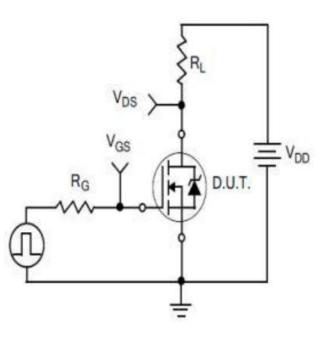


Figure C.
Resistive Switching Test Circuit

Figure B.
Gate Charge Waveform

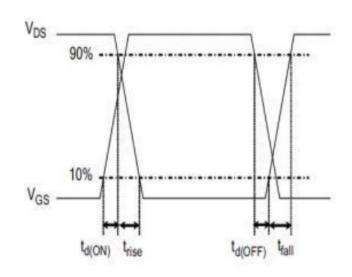
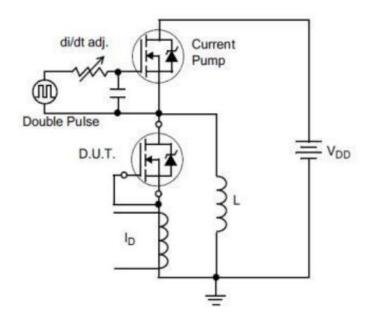


Figure D.
Resistive Switching Waveforms



### **Test ircuits and Waveforms**



 $di/dt = 100A/\mu A$   $Q_{rr}$ 

Figure E.Diode Reverse Recovery Test Circuit

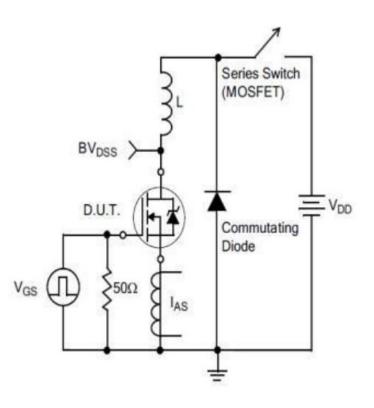


Figure F.Diode Reverse Recovery Waveform

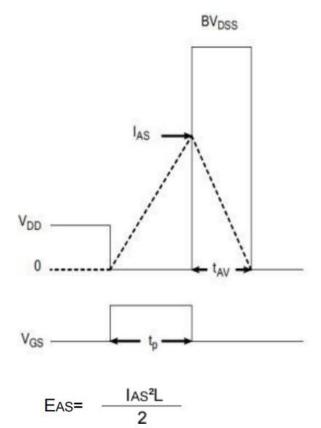
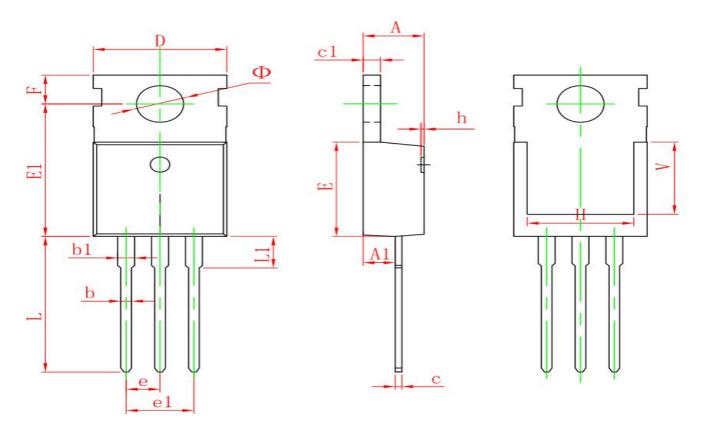


Figure G.Unclamped Inductive Switching Test Circuit

Figure H.Unclamped Inductive Switching Waveforms



# Package outline drawing(TO-220 Unit: mm)



Symbol	Dimensions	In Millimeters	Dimension	s In Inches	
Symbol	Min.	Max.	Min.	Max.	
Α	4.400	4.600	0.173	0.181	
A1	2.250	2.550	0.089	0.100	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
С	0.330	0.650	0.013	0.026	
c1	1.200	1.400	0.047	0.055	
D	9.910	10.250	0.390	0.404	
E	8.950	9.750	0.352	0.384	
E1	12.650	13.050	0.498	0.514	
е	2.54	TYP.	0.100	TYP.	
e1	4.980	5.180	0.196	0.204	
F	2.650	2.950	0.104	0.116	
Н	7.900	8.100	0.311	0.319	
h	0.000	0.300	0.000	0.012	
L	12.900	13.400	0.508	0.528	
L1	2.850	3.250	0.112	0.128	
V	6.90	REF.	0.276 REF.		
Φ	3.400	3.800	0.134	0.150	



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